

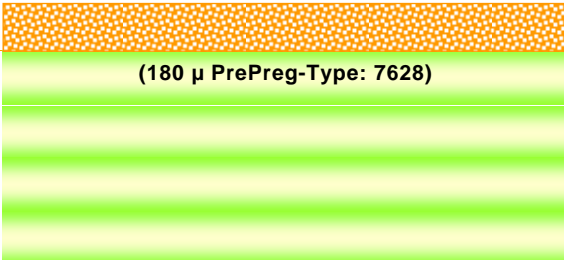
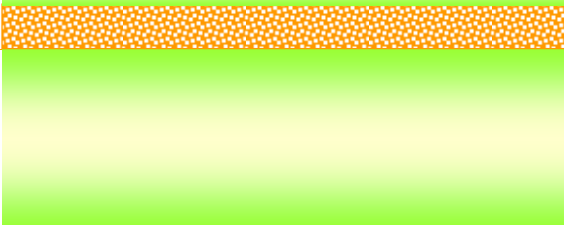
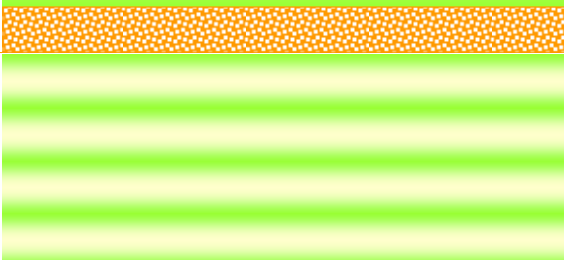

Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

04 322 FR4 70 L150.70 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_322_FR4_70_L150.70_p18

| Layers | in μ | Material | Build-Up | Assembly |
|-----------------|------------|----------|--|----------|
| Layer-1 | 70 μ | Copper |  | A1 |
| | 180 μ | Prepreg | | |
| | 180 μ | Prepreg | | |
| | 180 μ | Prepreg | | |
| | 180 μ | Prepreg | | |
| Layer-2 | 70 μ | Copper |  | B |
| | 1500 μ | L-FR4 | | |
| Layer-3 | 70 μ | Copper |  | A1 |
| | 180 μ | Prepreg | | |
| | 180 μ | Prepreg | | |
| | 180 μ | Prepreg | | |
| | 180 μ | Prepreg | | |
| Layer-99 | 70 μ | Copper |  | A1 |

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